



Features:

- Lower density
- High breakdown voltage
- Good heat spreader
- High volume resistivity
- Good EMC
- Ideal for direct metalisation
- Good thermal cycling stability

Applications:

- Metal heat sink replacement,
- LED, Chipset cooling, power modules, IC cooling

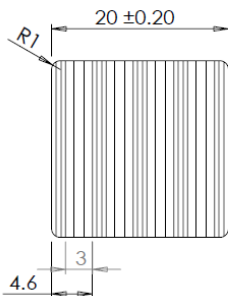
Property		Units	Value
Physical	Material	N/A	Al ₂ O ₃
	Density	g/cm ³	3.66
	Water absorption	%	0.002
	Acid resistance	mg/cm ³	≤ 0.2
	Alkali resistance	mg/cm ³	≤ 0.2
Mechanical	Mohs hardness	HV	9
	Bend Strength	MPa	≥610
	Compression Intensity	MPa	≥620
Thermal	Max. working temp.	°C	1400
	Thermal expansion coefficient	(1x10 ⁻⁶) mm/ °C	7.8 - 8.3
	Thermal Conductivity	W/m K	25
Electrical	Resisting rate of volume	Ω °C	1016
	DC breakdown strength	kV/mm	15.2 - 16.7
	Dielectric constant	(E)	18
	Dielectric dissipation	(tg o)	0.4 x 10 ⁻³

Part Number	Size	R _{th} (°C/W) at 100 lfm	R _{th} (°C/W) at 400 lfm	Dwg
SF-CHS-202003F	20x20x2.5mm	58.2	43.0	A
SF-CHS-252503F	25x25x2.5mm	45.4	31.5	B
SF-CHS-555506F	55x55x6mm	10.4	6.2	C
SF-CHS-707012F	70x70x12mm	4.3	2.4	D
SF-CHS-757506F	75x75x6mm	7.2	4.0	E
SF-CHS-858506F	85x85x6mm	5.8	3.1	F

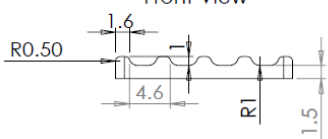
Drawing layouts:

Drawing A: 20x20x2.5mm

Top View

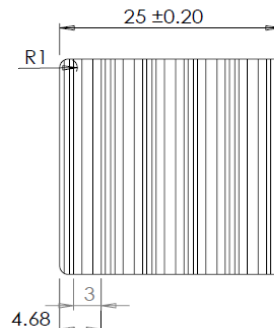


Front View

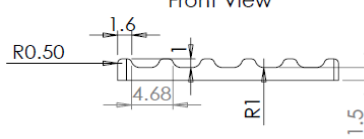


Drawing B: 25x25x2.5mm

Top View

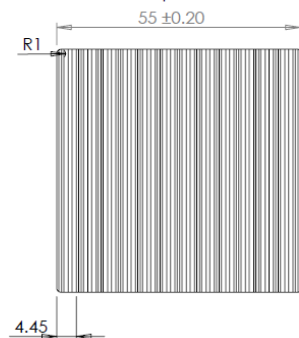


Front View

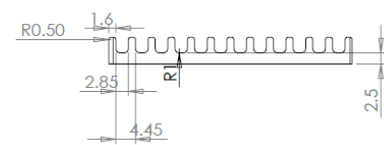


Drawing C: 55x55x6mm

Top View



Front View



Drawing layouts:

Drawing D: 70x70x12mm

Drawing E: 75x75x6mm

Drawing F: 85x85x6mm

